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Exensio™ IDM

End-to-End Data Management and Analytics for Integrated Device Manufacturers

Overview

Exensio™ IDM is PDF Solutions' end-to-end big data analytics product, architected for integrated device manufacturers, and built on our industry-leading Exensio™ Analytics Platform.

IDMs around the world rely on Exensio™ IDM to collect and align data from every step in the semiconductor product lifecycle. The data is available in near real-time via our Data Exchange Network (DEX) and is stored in a robust semantic data model that is immediately ready for interactive, automated, or machine-learning analytics.

Automatic data collection and management

With Exensio™ Fabless, engineers and data scientists no longer need to waste time and effort on data wrangling or data integration issues that typically consume up to 80% of the effort of data analysis projects.

24/7 Monitoring and protection of yield and quality

Exensio™ Fabless provides 24/7 monitoring and protection of your semiconductor devices during test operations, assembly, and packaging, and is the final gatekeeper for all of your devices before they are sent to your customers and into the supply chain.

High-performance, scalable environment

No other data analytics product has been designed and architected specifically for the semiconductor industry, and can scale to support the data and performance requirements of startup companies to Fortune 500 organizations.

Product Highlights

- Fully integrated, end-to-end analytics solution for integrated device manufacturers

- Data management for more than 50 different semiconductor data types

- Reduce data wrangling by up to 80%

- Improve product quality by up to 50%

- Fast, high-volume, and scalable yield management environment

- Complete lot and wafer genealogy

- Bi-directional tester control

- Inkless wafer map editing, merging and exporting

- Online and offline rules for quality and reliability

- Single Device Traceability (SDT) with support for ECIDs

Exensio™ Fabless

End-to-End Data Management and Analytics

Assembly Operations · **Test Operations** · **Manufacturing Analytics** — exensio™ Fabless

A single point of truth for all of your product data

Comprehensive support for data collection

Test Operations

>20 Vendors   **>50** Tester/Prober/Handler Models

ADVANTEST · Agilent Technologies · ACCRETECH · EAGLE TEST SYSTEMS · electroglas · LTX-Credence · mct · MICRO-TEST · NATIONAL INSTRUMENTS · Roos Instruments · Schlumberger · SPEA · TEL · TERADYNE · Tesec. · VERIGY · Xcerra

Assembly Operations

>50 Vendors   **>150** Equipment models

ASM · Besi · Canon · CREDEN · Datacon · EO TECHNICS · PASFORD TECHNOLOGY · FEK DELVOTEC · FUJI · Giga-tronics · HANMI · HOVERDAVIS · ismeca · JUKI · K · LAURIER · MIT · Mühlbauer · multitest · NDC International · Nidec · Panasonic · RENESAS · rofin · ROYCE · RUDOLPH · SHIMURA · SOLVISION · STI · TORAY · Universal

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Core Product Modules in Exensio™ Fabless

■ **Manufacturing Analytics:** The foundational module of Exensio™ Fabless that automatically collects and manages all front-end and back-end product data for rapid, advanced analytics for yield management, diagnostics, and root cause analysis

■ **Test Operations:** Automatically collect, analyze, and detect statistical changes in manufacturing test that negatively impact product yield, quality, or OEE, wherever those operations occur in your supply chain.

■ **Assembly Operations:** Enable the traceability of wafers, die, and multi-chip modules through assembly and packaging, with or without ECIDs. Provides full visibility into assembly line processes to accelerate new product introductions.

Exensio visualizations Powered by Spotfire®

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